

MODIFIABLE SEMICONDUCTOR CIRCUIT ELEMENT

Abstract

An integrated circuit chip (10) having a substrate (36) with several overlaying metal layers (M3, M4). A lower metal layer (M3) is adjacent the substrate and an upper layer (M4) is spaced above the lower layer. The chip has circuitry including a number of circuit elements (16), and a number of access elements (20), each associated with and electrically connected to one of the circuit elements. Each access element includes first and second terminals (32, 34) in the lower layer, and an elongated span element (30) in the upper layer. The span element has a first end overlaying and electrically connected to the first terminal and a second end overlaying and electrically connected to the second terminal. One of the terminals may be connected to provide power or a connection to the input or output of the associated circuit element. The chip may then be modified by severing the span element, or by connecting the span element to other circuitry on the chip to disable or enable operation of the circuit element.

Figure 4

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